

ABSTRACT

LEAD-FREE SOLDER ALLOY

5 A lead-free solder which is comprised of three elements Sn-Cu-Ni. Cu and Ni are 0.1 - 2 wt% and 0.002 - 1 wt% respectively. Preferable weight percentage of Cu and Ni are 0.3 to 0.7 percent and 0.04 to 0.1 percent respectively. Both methods of additive Ni to a base alloy of Sn-Cu and additive Cu to a base alloy of Sn-Ni are applicable.